

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 05-299470

(43)Date of publication of application : 12.11.1993

(51)Int.Cl.

H01L 21/60
H01L 23/34

(21)Application number : 04-125643

(71)Applicant : MEGA CHIPS:KK

(22)Date of filing : 16.04.1992

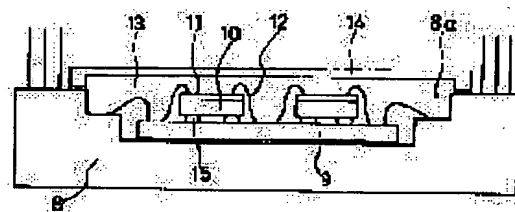
(72)Inventor : YOSHIMIZU TOSHIKAZU
UKAI YUKIHIRO

(54) SEMICONDUCTOR DEVICE

(57)Abstract:

PURPOSE: To improve radiation without requiring a radiating resin, a radiating material, and its sealing step for a multi-chip module using face-down bonding.

CONSTITUTION: A metallic layer 11 is mounted on the rear face of an IC chip 10, which is mounted on a base board 9 in a face-down bonding step, and the metallic layer 11 and the base board 9 are connected with a radiating bonding wire 12 to improve radiating characteristics.



LEGAL STATUS

[Date of request for examination]	29.03.1999
[Date of sending the examiner's decision of rejection]	21.08.2001
[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]	
[Date of final disposal for application]	
[Patent number]	3267671
[Date of registration]	11.01.2002
[Number of appeal against examiner's decision of rejection]	2001-16752
[Date of requesting appeal against examiner's decision of rejection]	20.09.2001
[Date of extinction of right]	

Copyright (C); 1998,2003 Japan Patent Office